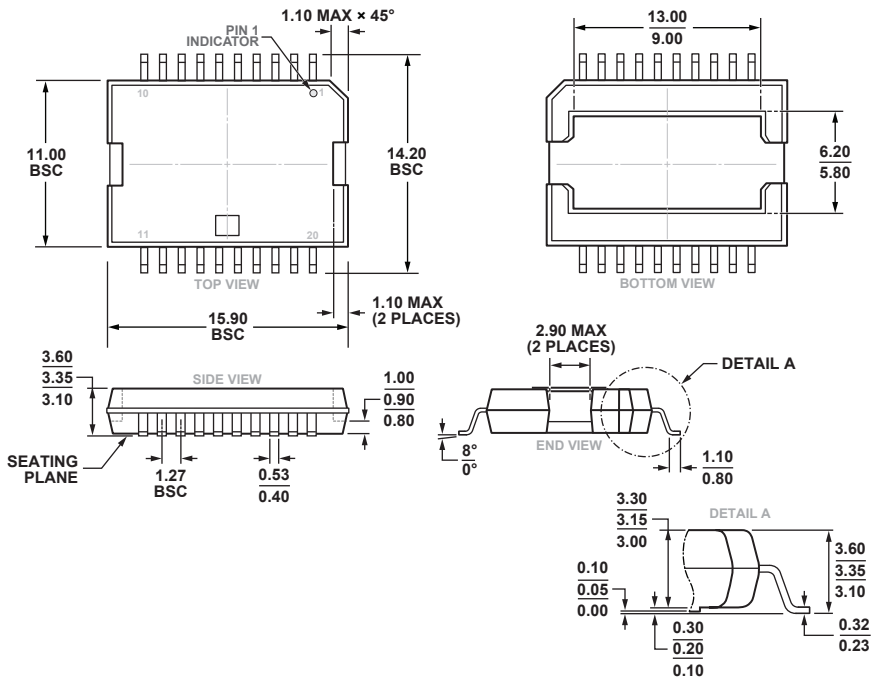


20-Lead Power SOIC, Thermally Enhanced Package [PSOP_3]
(RR-20-1)

Dimensions shown in millimeters



COMPLIANT TO JEDEC STANDARDS MO-166-AA